

HIKVISION FLIP-CHIP COB LED

Ultimate imaging through trail-blazing technology



PIXEL PITCH OPTIONS: P0.9, P1.2



Flip Chip COB technology achieves higher contrast ratios and lower dead pixel rates by 10 PPM*



The front bearing force gets a boost with epoxy resin, with water and dust resistance at IP65 levels



Flip Chip COB removes lamp wires for lower power consumption by up to 40%

*Flip Chip COB is one of the most advanced technologies available. The electrodes are connected to the PCB board directly, so bonding wires are no longer needed.

*PPM stands for Pixels per Million